

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YUTAKA KOUZUMA	03/15/2019
MICHIAKI KOBAYASHI	03/15/2019
KAZUYUKI HIROZANE	03/15/2019
NOBUYA MIYOSHI	03/16/2019
KOHEI KAWAMURA	03/15/2019
HIROYUKI KOBAYASHI	03/15/2019
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<b>Name:</b>	HITACHI HIGH-TECHNOLOGIES CORPORATION
<b>Street Address:</b>	24-14, NISHI-SHIMBASHI 1-CHOME
<b>City:</b>	MINATO-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	29677764
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	100929.DA356US
<b>NAME OF SUBMITTER:</b>	LISA A. ADELSON
<b>SIGNATURE:</b>	/Lisa A. Adelson/
<b>DATE SIGNED:</b>	04/04/2019
<b>Total Attachments: 4</b> source=DA356US_Assignment#page1.tif	

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source=DA356US\_Assignment#page3.tif  
source=DA356US\_Assignment#page4.tif

22,186,0022

ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me, by **Hitachi High-Technologies Corporation**, a corporation organized under the laws of **Japan**, located at **24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan**, receipt of which is hereby acknowledged, I do hereby sell and assign to said **Hitachi High-Technologies Corporation**, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

**INTEGRATED TYPE ION SHIELD FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, Serial No. **29/677,764**, filed on **January 23, 2019**, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said **Hitachi High-Technologies Corporation**, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **Hitachi High-Technologies Corporation**.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) Yutaka Kouzuma  
Yutaka KOUZUMA

3 / 15 / 2019

2) \_\_\_\_\_  
Michiaki KOBAYASHI

ASSIGNMENT  
( 譲渡証 )

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And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **Hitachi High-Technologies Corporation**.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) _____ Yutaka KOUZUMA	_____
2) <u>Michiaki Kobayashi</u> Michiaki KOBAYASHI	<u>03 / 15 / 2019</u>

INVENTOR(S)  
(発明者フルネームサイン)

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3) Kazuyuki Hirozane 3 / 15 / 2019  
Kazuyuki HIROZANE

4) \_\_\_\_\_  
Nobuya MIYOSHI

5) Kohei Kawamura 3 / 15 / 2019  
Kohei KAWAMURA

6) Hiroyuki Kobayashi 3 / 15 / 2019  
Hiroyuki KOBAYASHI

INVENTOR(S)  
(発明者フルネームサイン)

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(署名日)

3)	_____	_____
	<b>Kazuyuki HIROZANE</b>	
4)	Nobuya Miyoshi _____	3/16/2019 _____
	<b>Nobuya MIYOSHI</b>	
5)	_____	_____
	<b>Kohei KAWAMURA</b>	
6)	_____	_____
	<b>Hiroyuki KOBAYASHI</b>	